Global Communication Semiconductors, LLC
Corporate & Foundry
23155 Kashiwa Court, Torrance, CA. 90505
Telephone: 310-530-7274 Fax: 310-517-8200
Website: www.gcsincorp.com

Job Title:	**Process Engineer**
Job Req.	#0665
Department:	Quality Assurance
Status:	Full-Time / Exempt

Job Description

- Experience and knowledge in semiconductor wafer process for RF, power, and optical components.
- Experience and skills in backside processing of semiconductor devices and circuits including, but not limited to:
- Wafer mounting, wafer thinning (lapping, polishing, grinding, CMP, etc.)
- Wafer dicing (laser scribing, dicing, scribe and break, saw)
- Die separation and picking
- Die packaging, including wire bonding
- Die shear and wire pull
- Knowledge or experience in programming automated optical inspection (AOI) for semiconductor wafers.
- Ability to develop AOI protocol and semiconductor wafer backend processes for manufacturing optimization.
- Resolution and disposition of process issues related to backend areas.
- Creation and maintenance of standards and documents for backend equipment operation, training, and maintenance.
- Training of operators, technicians and engineers.

Job Requirements

- BS, MS degree in engineering or related field
- Must have clean room and hands-on wafer processing experience
- Experience in automated optical inspection and wafer scribe/break or sawing process preferred
- Ability to effectively communicate and interact with all other employees at all levels, vendors, customers, and management in a professional manner
- Ability to effectively work in a fast-paced environment, with shifting priorities, to support overall business objectives
- Strong knowledge in automated optical inspection and wafer scribe/break or sawing process
- Good Excel and document drafting skills